

Features

- Advanced high cell density Trench technology
- Low $R_{DS(ON)}$
- High Current Capability
- Green Device Available

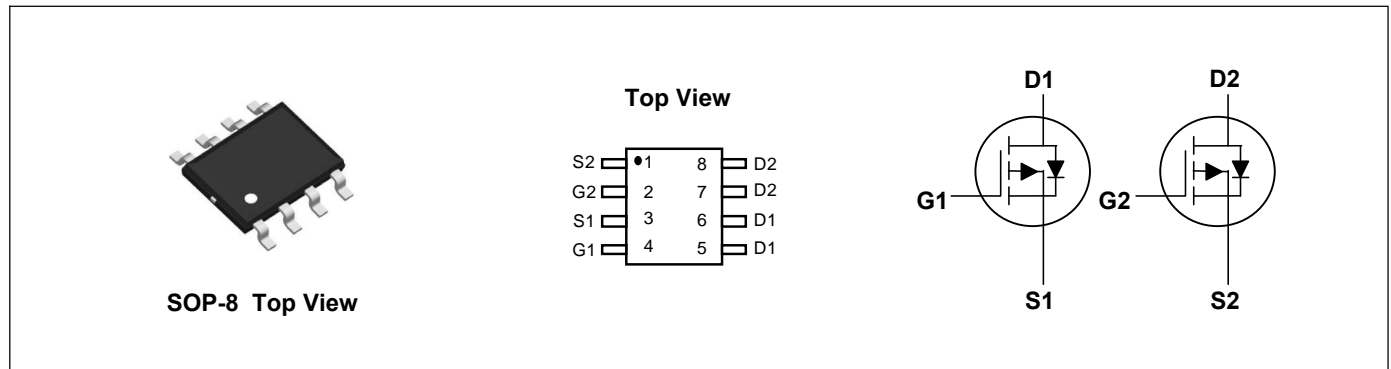
Product Summary



V_{DS}	-30	V
I_D	-7.6	A
$R_{DS(ON)}$ (at $V_{GS}=-10V$)	55	m Ω
$R_{DS(ON)}$ (at $V_{GS}=-4.5V$)	65	m Ω

Applications

- High Frequency Point-of-Load, Synchronous Buck Converter for MB/NB/UMPC/VGA
- Battery Protection Charge/Discharge
- Load Switch



Absolute Maximum Ratings ($T_A=25^\circ\text{C}$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D@T_A=25^\circ\text{C}$	-7.6	A
Continuous Drain Current	$I_D@T_A=70^\circ\text{C}$	-6.1	A
Pulsed Drain Current ²	I_{DM}	-38	A
Total Power Dissipation ³	$P_D@T_A=25^\circ\text{C}$	2	W
Total Power Dissipation ³	$P_D@T_A=70^\circ\text{C}$	1.28	W
Storage Temperature Range	T_{STG}	-55 to 150	$^\circ\text{C}$
Operating Junction Temperature Range	T_J	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Ambient ¹ ($t \leq 10\text{s}$)	$R_{\theta JA}$	48	62.5	$^\circ\text{C/W}$
Thermal Resistance Junction-Ambient ¹ (Steady State)		74	90	$^\circ\text{C/W}$
Thermal Resistance Junction-Lead (Steady State)	$R_{\theta JL}$	32	40	$^\circ\text{C/W}$

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =-250uA	-30	---	---	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =-10V, I _D =-7.6A	---	45.5	55	mΩ
		V _{GS} =-4.5V, I _D =-7A	---	57.5	65	mΩ
		V _{GS} =-2.5V, I _D =-6A	---	75	85	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =-250uA	-0.6	-0.9	-1.5	V
On state drain current	I _{D(ON)}	V _{GS} =-10V, V _{DS} =-5V	-38	---	---	A
Drain-Source Leakage Current	I _{DSS}	V _{DS} =-20V, V _{GS} =0V, T _J =25°C	---	---	-1	uA
		V _{DS} =-20V, V _{GS} =0V, T _J =55°C	---	---	-5	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
Forward Transconductance	g _{fs}	V _{DS} =-5V, I _D =-7.6A	---	25	---	S
Gate Resistance	R _g	V _{DS} =0V, V _{GS} =0V, f=1MHz	0.8	1.7	2.6	Ω
Total Gate Charge (10V)	Q _g	V _{DS} =-15V, V _{GS} =-10V, I _D =-7.6A	---	12.5	---	nC
Total Gate Charge (4.5V)	Q _g		---	6	---	
Gate-Source Charge	Q _{gs}		---	1	---	
Gate-Drain Charge	Q _{gd}		---	2	---	
Turn-On Delay Time	T _{d(on)}	V _{DS} =-15V, V _{GS} =-10V, R _L =1.3Ω, R _G =3Ω	---	3	---	ns
Rise Time	T _r		---	7.5	---	
Turn-Off Delay Time	T _{d(off)}		---	20	---	
Fall Time	T _f		---	6	---	
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V, f=1MHz	---	525	630	pF
Output Capacitance	C _{oss}		---	95	125	
Reverse Transfer Capacitance	C _{rss}		---	75	105	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Continuous Source Current ^{1,4}	I _S	V _G =V _D =0V, Force Current	---	---	-2.5	A
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V, I _S =-1A, T _J =25°C	---	-0.7	-1	V
Reverse Recovery Time	t _{rr}	I _F =-7.6A, di/dt=100A/μs, T _J =25°C	---	14	---	nS
Reverse Recovery Charge	Q _{rr}		---	6	---	nC

Note:

- The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- The power dissipation is limited by 150°C junction temperature
- The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

Typical Characteristics

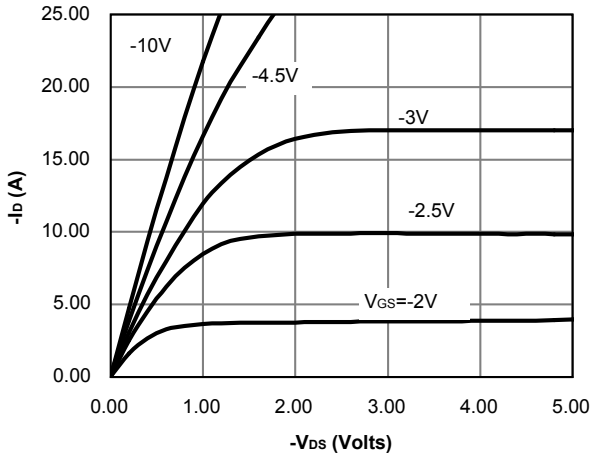


Fig 1: On-Region Characteristics

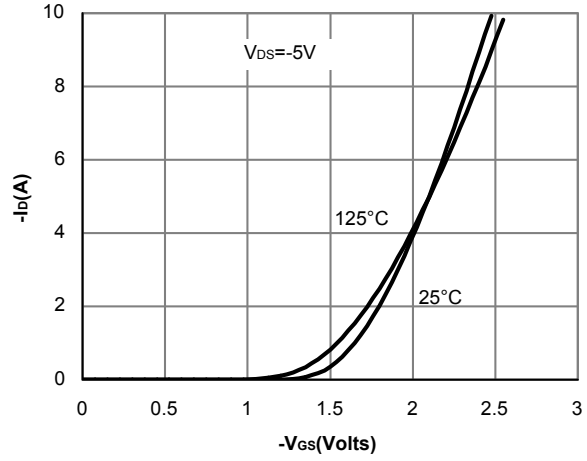


Figure 2: Transfer Characteristics

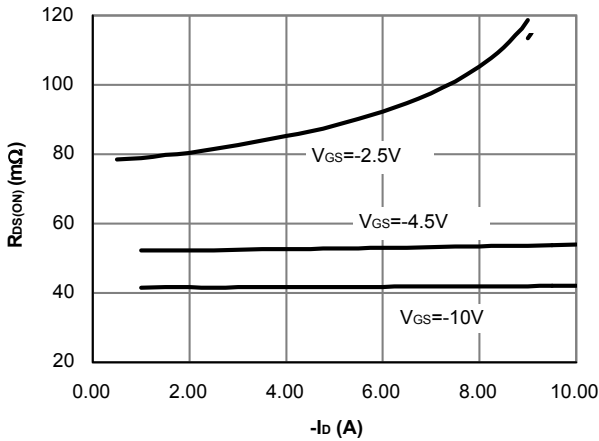


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

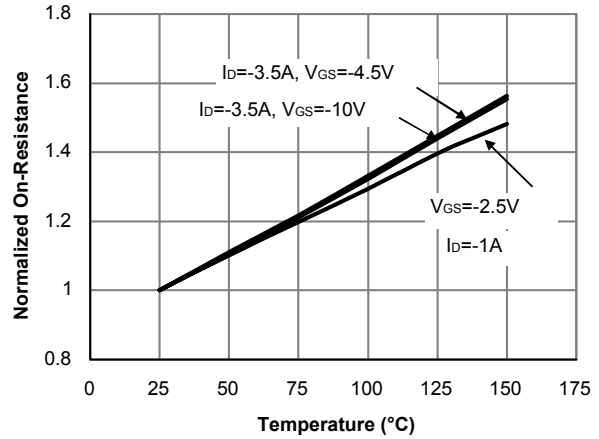


Figure 4: On-Resistance vs. Junction Temperature

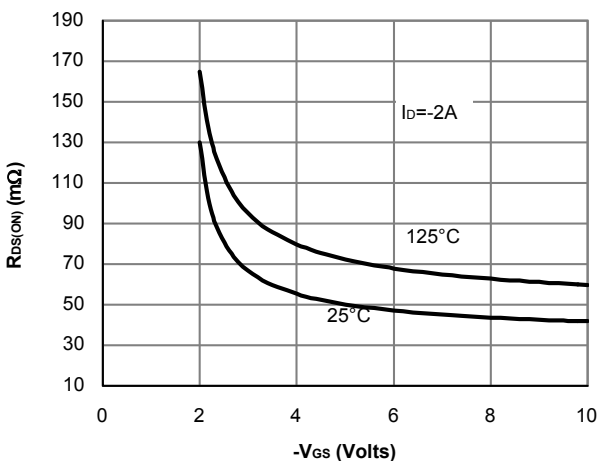


Figure 5: On-Resistance vs. Gate-Source Voltage

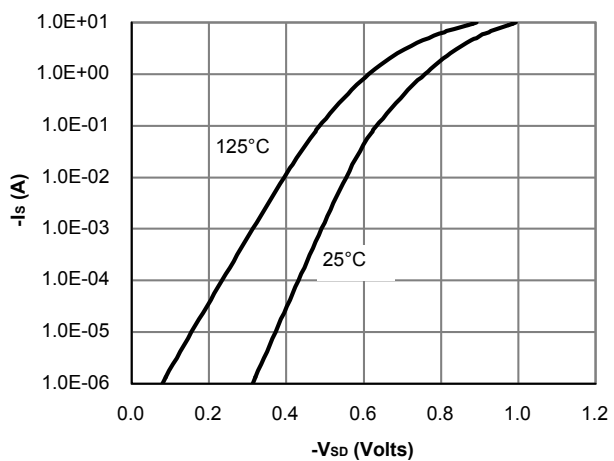


Figure 6: Body-Diode Characteristics

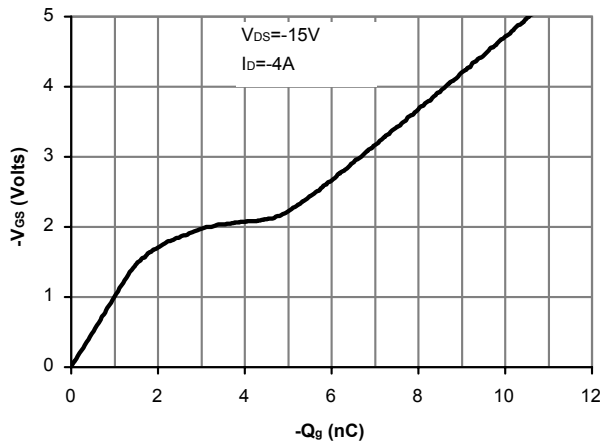


Figure 7: Gate-Charge Characteristics

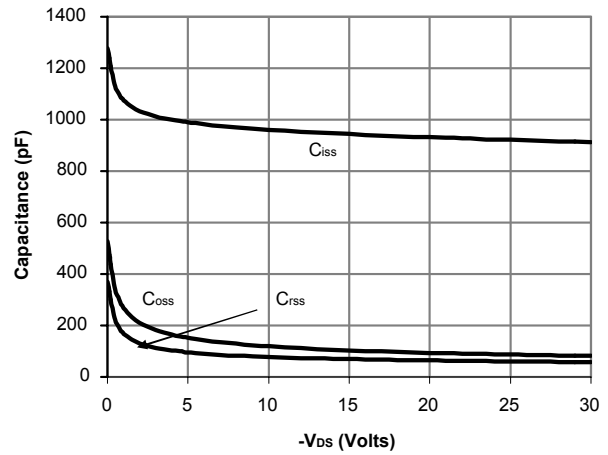


Figure 8: Capacitance Characteristics

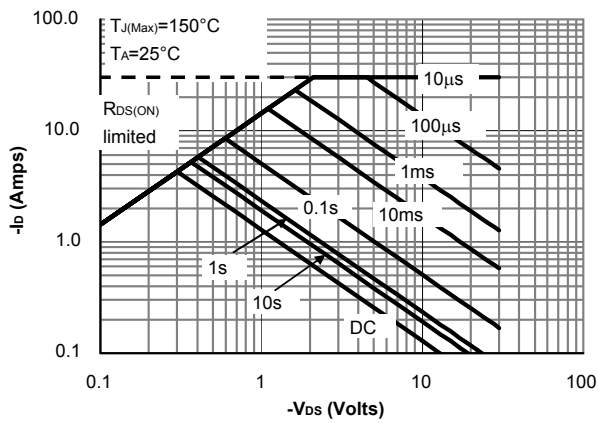


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

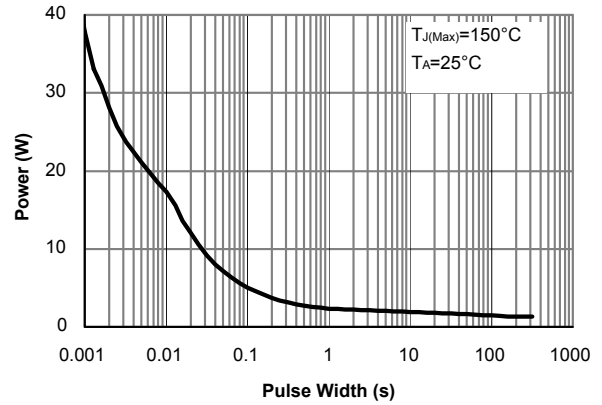


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

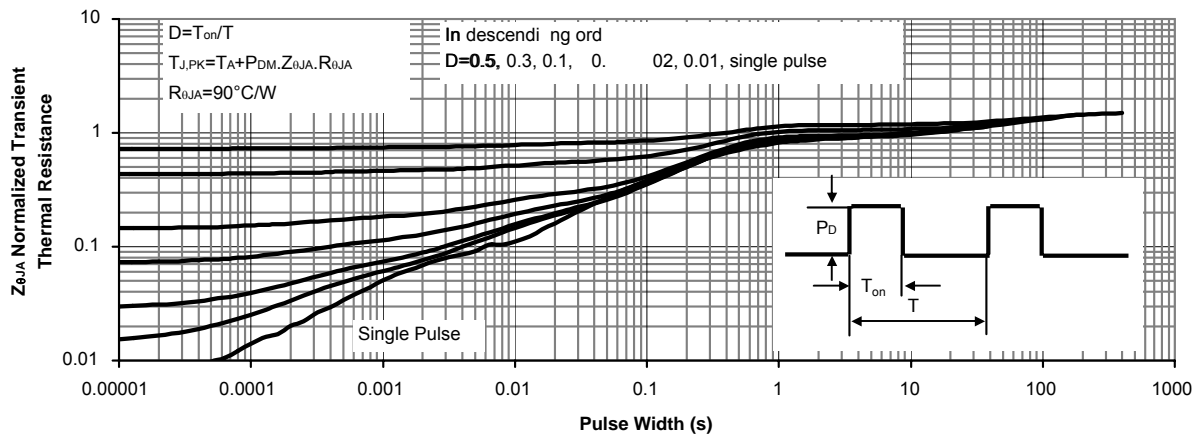
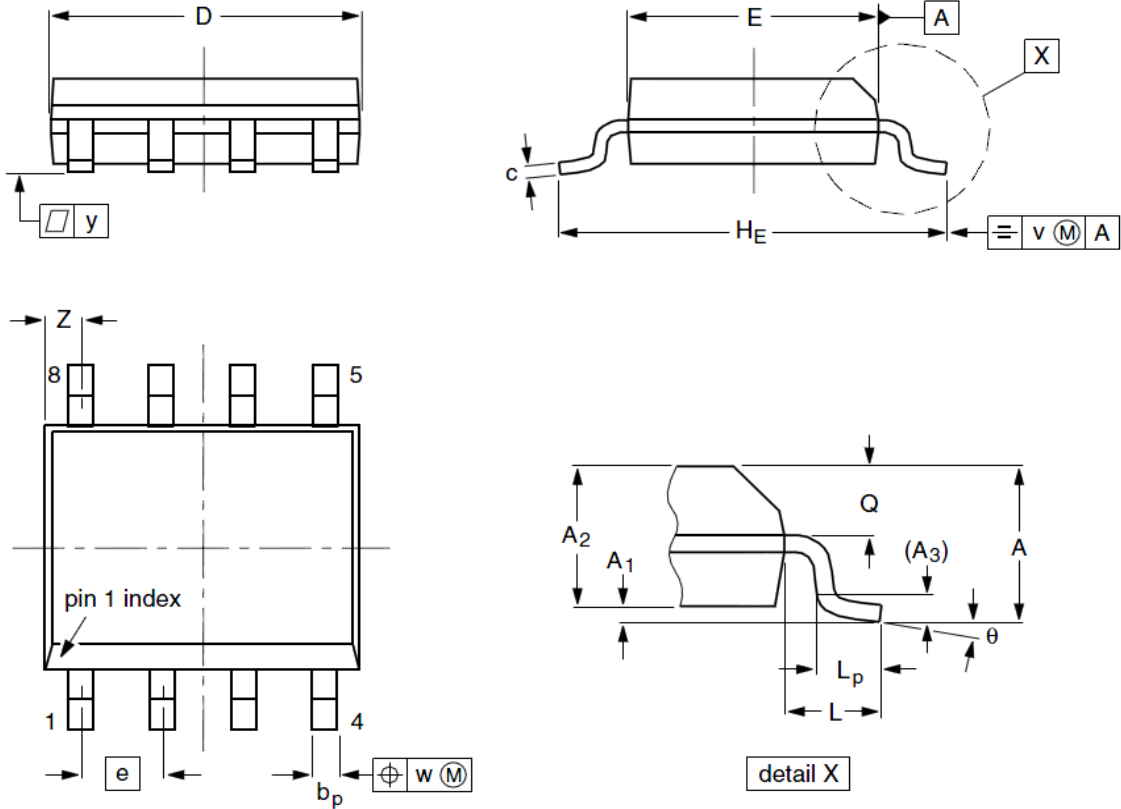


Figure 11: Normalized Maximum Transient Thermal Impedance

SOP-8 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	1.35	1.55	1.75	A₁	0.10	0.18	0.25
A₂	1.25	1.45	1.65	A₃	--	0.25	--
b_p	0.36	0.42	0.51	c	0.19	0.22	0.25
D	4.70	4.92	5.10	E	3.80	3.90	4.00
e	--	1.27	--	H_E	5.80	6.00	6.20
L	--	1.05	--	L_p	0.40	0.68	1.00
Q	0.60	0.65	0.73	v	--	0.25	--
w	--	0.25	--	y	--	0.10	--
Z	0.30	0.50	0.70	θ	0°		8°